

ICS 31.200
CCS L55



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 15879.613-2026

**Mechanical standardization of semiconductor devices - Part
6-13: Design guideline of open-top-type sockets for Fine-pitch
Ball Grid Array (FBGA) and Fine-pitch Land Grid Array (FLGA)**

半导体器件的机械标准化 第6-13部分：密节距焊球阵列封装（FBGA）和密节距
焊盘阵列封装（FLGA）顶部开放式插座的设计指南

(English Translation)

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Foreword

GB/T 15879.613-2026 is a recommended national standard (GB/T) of the People's Republic of China, issued on 28 August 2026 by the State Administration for Market Regulation and the Standardization Administration of China, with effect from 1 March 2027.

The document adopts an international standard (ISO or IEC).

It is under the responsibility of the Ministry of Industry and Information Technology (Electronics).

Classification: ICS 31.200; CCS L55.

1 Scope

Test and burn-in sockets allow fine-pitch ball grid array and land grid array packages to be connected without soldering. This document is Part 6-13 of the series on mechanical standardization of semiconductor devices and provides a design guideline for open-top-type sockets for fine-pitch ball grid array (FBGA) and fine-pitch land grid array (FLGA) packages.

Socket manufacturers can use it to align their designs with a common outline, and semiconductor makers and test houses may refer to it when specifying the sockets used for device qualification and production test. Board designers who need to plan for a socketed device can also benefit from a shared mechanical reference. As the title says, it is a guideline, and it is a recommended national standard that adopts an international standard. It was issued on 28 August 2026 and takes effect on 1 March 2027.